

SUBSTRATE WASHING DEVICE

CROSS-REFERENCE TO RELATED APPLICATIONS

[0001]

This application claims the benefit of Japanese Priority Patent Applications JP 2016-093756 and JP 2016-093755 filed on May 09, 2016 the entire contents of which are incorporated herein by reference.

FIELD

[0002]

The present technology relates to a substrate washing device which washes a surface of a substrate by using a two-fluid jet.

BACKGROUND AND SUMMARY

[0003]

As a method for washing a surface of a substrate in a noncontact manner, a washing method using a two-fluid jet (2FJ) has been conventionally known. In such 2FJ-washing, fine droplets (for example, pure water mist) included in high-speed gas (for example, CO₂ gas) are ejected from a two-fluid nozzle toward a surface of a substrate so as to collide with the surface, and particles, etc. on the surface of the substrate are removed (washed away) by using shock waves caused by collision of the droplets with the surface of the